

Investor Relations 2019

Disclaimer

This Document contains forward-looking statements that reflect INNOX Group's current views about future events. The words, "anticipate," "assume," "believe," "estimate," "expect," "intend," "may," "can," "could," "plan," "project," "should" and similar expressions are used to identify forward-looking statements.

These statements are subject to many risks and uncertainties or may be affected by factors outside INNOX Group's control.

This includes adverse developments in global economic conditions resulting in decline in demand in INNOX Group's key markets including Korea, Japan, East Asia and North America;

- 1 a deterioration in credit and financial markets;
- 2 a shift in consumer preferences affecting demand for Innox group's products;
- 3 changes in the prices of fuel or raw materials;
- 4 disruption due to shortages of materials;
- (5) disruption of production due to shortages of materials,
- 6 labor strikes or supplier insolvencies;
- 7) the effective implementation of Innox Group's strategic goals and targets;
- ® changes in laws, regulations and government policies, particularly those relating to vehicle emissions, fuel economy and safety;
- (9) and other risks and uncertainties.

If any of these risks and uncertainties materializes or if the assumptions underlying any of INNOX Group's forward-looking statements prove to be incorrect, actual results may be materially different from those INNOX Group expresses or implies by such statements. INNOX Group does not intend or assume any obligation to update these forward-looking statements.

OVERVIEW



Corporate	INNOX Advanced Materials Co., Ltd Chang, Gyung Ho & Kim, Pil Young (Separate Representation)		
CEO			
Foundation	Nov 8th 2001 (Spilt-Up. Jun 1th 2017)		
Issued Shares	9,232,420 (INNOX 33.7%)		
Capital	KRW 46.2B		
Homepage	www.innoxamc.com		
Address	171, Asan Valley-ro, Dunpo-myeon, Asan-Si Chungcheongnam-do, South KOREA		



Main Business



OLED/DISPLAY MATERIALS



SEMICONDUCTOR PACKAGING MATERIALS







NEXT GENERATION CIRCUIT MATERIALS

^{*} The Figures are Data of the end of 2018

GET TO KNOW THE CEO





CHAIRMAN Chang, Kyeong Ho

Born in 1958

KAIST
Doctor of MSE
(Material Science & Engineering)

SAMSUNG TECHNOLOGY
Chief Researcher

INNOX Founder



PRESIDENT Kim, Pil Young

Born in 1958

Kyungpook University
Bachelor of Electronics

SAMSUNG ELECTRONICS Executive

SAMSUNG FIBEROPTICS
President

BUSINESS PRINCIPLES

Growth

Achieve \$ 1 billion in revenue base on continuous growth and business diversification

Ethic

Transparent & ethical management through principles and standards

Survival

Securing sustainability of business through competitiveness of R&D

Safety

Absolute value of safety, Establishment of sound corporate culture

BRIEF HISTORY OF COMPANY













	Foundation 2001 ~ 2002	200120012002	Founded Saehan Micronics Established SEM-1(Plant1) Established R&D Center
	Turning Point 2003 ~ 2007	2005 2006 2006	Change Company Name and CI Listed on KOSDAQ Completed SEM-3 Anseong Plant2
	Growth 2008 ~ 2011	2010 2010 2011	Become global #1 player : FPCB material business FCCL products designated as 'World Best Product' Established new Asan Plant
	Take Off 2012 ~ 2016	2014 2015 2016	Launching INNOLED Taking over acquired Alton Sports Established the I-Best
	Launch of H/C	2017 2018 2018	(INNOX / INNOXAMC) Split(Divided) Establishment Production Plant in China & Vietnam Awarded Export Tower Award of US\$100 million

KEY TAKEAWAYS



Over 50% Non-FPCB Materials

- Expand Product Mix of OLED/SEM* Materials
- A Portion of OLED Materials Sales More Than 50%

1 Abroad Production Facility CAPA' UP

- Build UP DSP* Factory in Guangzhou, China
- Build UP EM* Factory in Bac Ninh, Vietnam
- Increase Total Production Volume Capacity in 2019

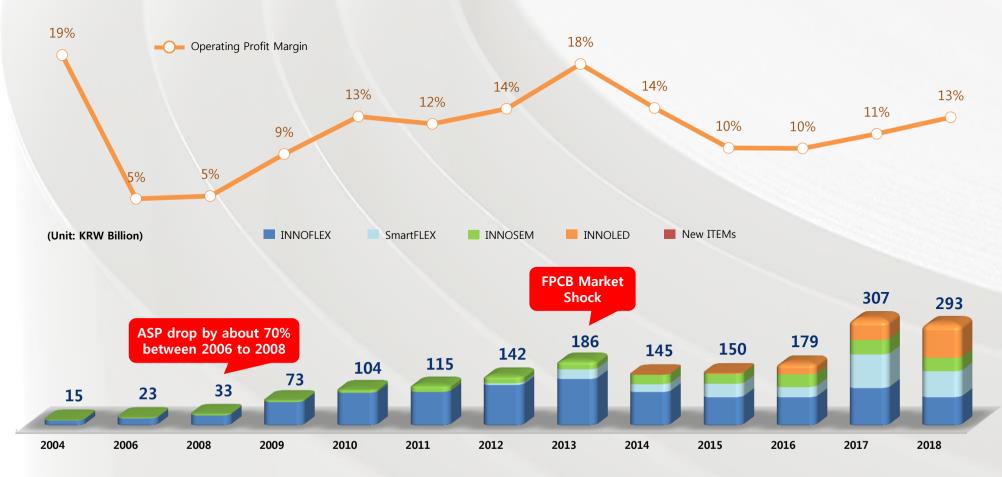
Scale Up Product Mix through R&D (Annually Invest more than 5% of Sales)

- The Fourth Industrial Revolution, We are aggressive responding of the new material era (Foldable, AI, 5G, etc..)
- Increase Global M/S* Through Improving Performance of Products and Low Cost Technology

REVENUE & PROFIT



The CAGR* of Revenue from 2003 to 2018 is 35%, OPM* More Than 11% Growth REVENUE & PROFIT through OLED and NEW Materials From 2017



^{*} CAGR: Compound Annual Growth Rate, AAGR: Average Annual Growth Rate, OPM: Operating Profit Margin

CORE TECHNOLOGY



Core Technology & Competitiveness

- * Competitiveness : Chemical Base EM Development
 - Adhesive & Formulation
- * Technology: Process Engineering & Control
 - Facility Design, Clean Class Management
- * ERP & SCM Base Management
 - Quality Control and Cost Competitiveness

Major R&D Achievements

Most of the Products

- First in KOREA or Global No. 2~3
- Develop Independent Technology
- Fast Follower of Japanese Products to First Mover

OLED Materials: Encapsulation film, B/P, PSA film ...

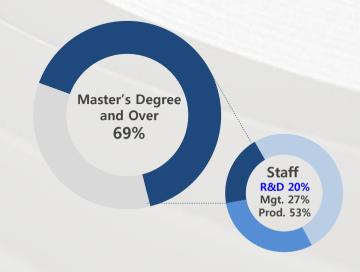
Semiconductor Materials: DAF, QFN, LOC, LLT ...

Circuit Materials: H/S, Coverlay, FCCL, Stiffener, Digitizer ...

R&D Center

Foundation	2002		
Researcher	120 (20% of total employee)		
Field	OLED/SEM/Circuit, New Business, Technology Planning		
Intellectual property	58 Patents (53 Domestic, 5 oversea patents)		

^{*} Technology has accumulated for 25 years (Samsung Advanced Institute of Technology → Saehan Micronics → INNOX)



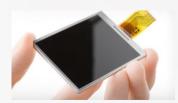
BUSINESS PORTFOLIO





INNOLED[®]
OLED & DSP Materials

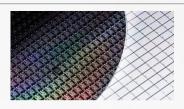






INNOSEM®
SEM Package Materials







TECHNOLOGICAL CONVERGENCE









INNOFLEX®
FPCB Materials





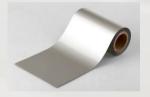


Design & Processing Adhesive

NEW BUSINESSAutomobile Materials
BIO/NANO Materials







OLED & DISPLAY(DSP) MATERIALS

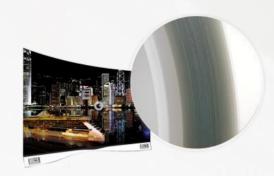


INNOLED®

New Growth Potential: Our Materials Meet Changing Form Factor

Through The Sustainable Research Activities since 2010

→ Launch Large-Size(TV) Materials in 2015 and Small-Size(Mobile) Materials in 2017 Main Mobile Applications DSP type: Curved, Edge, Foldable, Bendable, Unbreakable ...



Supply Chain











SEM PACKAGING MATERIALS



INNOSEM®

The Processing Materials for High Integrated/Multiple Layer Wafer Packaging

Just a Handful of Companies Control The SEM PKG Materials Business Through Ceaseless Technological Development and Challenges,

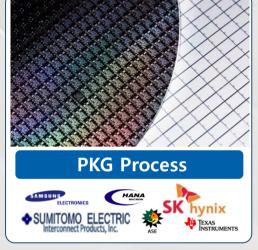
➡ Korea's Only SEM PKG Partner and is Working to Increase Global Market Share



Supply Chain











ADVANCED CIRCUIT MATERIALS



SMARTFLEX®

Extend Product Mix and M/S Based on Proprietary Technology

Essential Materials for State-of-the-Art Advanced Electronics, Smart & Mobile Device Main Applications: Tablet, High-end Smart Phone..



INNOFLEX®

To Hold on No.1 M/S, By Expanding Product Mix & Customer Lock-In Strategy

Supply to Core Materials and Many Adhesive Sheets for Used For Manufacturing FPCB Main Applications: Smart/Feature Phone, Smart Pad, PC, HDD, Automobile..

Supply Chain







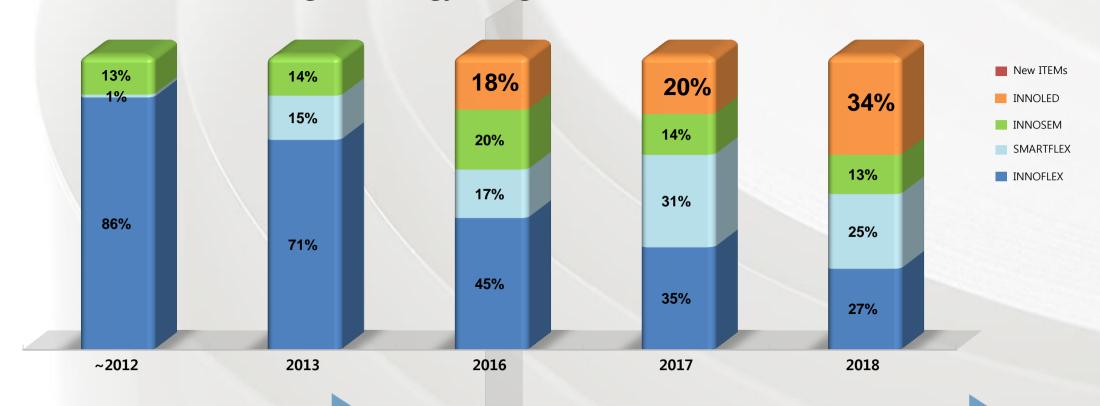




EXPAND PRODUCT MIX



Growth From FPCB Material Company To IT Total Advanced Material Company That is A Strong Technology Background of OLED & SEMICONDUCTOR



FPCB Material OVER 50%

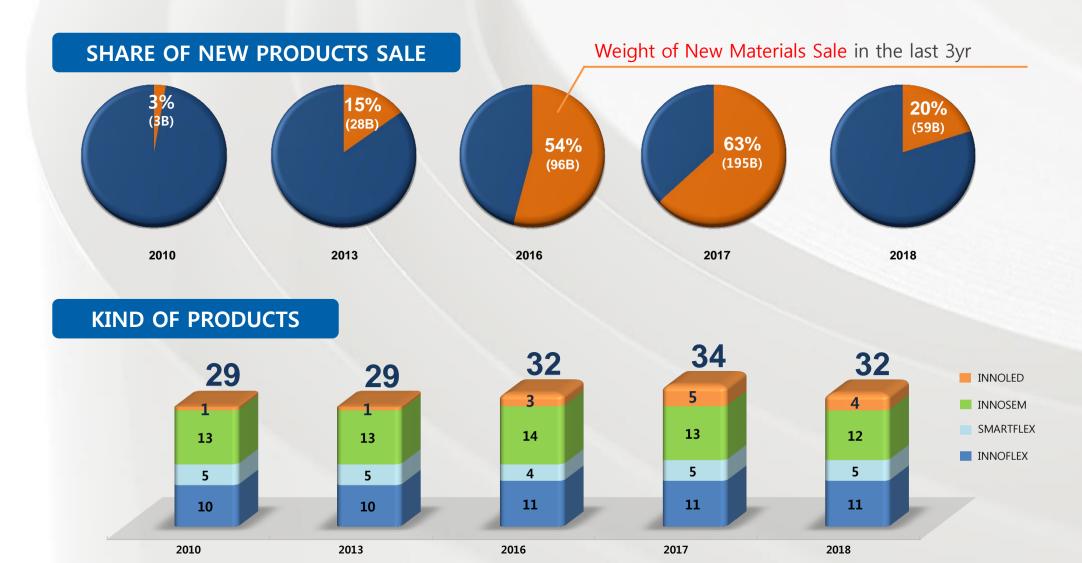
BUSINESS Inflection Point

OLED Material OVER 40%

INCREASE NEW MATERIALS SALE



Take Advantage Of OUR R&D System, Steadily Increasing Sales Volume of New Products



DOMESTIC FACTORIES



